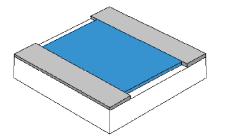
www.resistor.com

State of the Art, Inc.

02/03/05

S0303AF High Frequency Thin Film Chip Resistor

Standard Grade, Surface Mount, Top Surface Terminations



MECHANICAL	INCHES	MILIMETERS
Length Width Thickness Top Term Gap Approx. Weight	.032 (.030038) .030 (.028032) .010 (.008018) .008 (.003013) .015 (.011019) .00059 grams	0.82 (0.77 - 0.97) 0.75 (0.70 - 0.80) 0.25 (0.20 - 0.45) 0.20 (0.08 - 0.33) 0.37 (0.27 - 0.47)

CHARACTERISTICS

Resistance (others available) Tolerance (others available)	50, 75,100, 200 ohms 0.1,1, 2, 5 %
Maximum Power	50 milliwatts
Frequency Range	DC to 20 GHz
TCR (-55° / + 1Ž5°C)	25, 50, 100 ppm/°C

ENVIRONMENTAL PERFORMANCE*

Thermal Shock	±0.03 %
Low Temperature Operation	±0.03 %
Short Time Overload	±0.03 %
Resistance to Bonding Exposure	±0.03 %
Moisture Resistance	±0.05 %
High Temperature Exposure	±0.05 %

' Typical percent resistance change -test methods and actual specification limits are in accordance with Mil-PRF-55342.

TYPICAL LIFE PERFORMANCE

Parts are solder mounted on Fr4 board and tested at 70°C. Power is applied for 90 minutes on and 30 minutes off at a rate that achieves a film temperature 30°C above ambient.

e a	0.5									
nt										
cel Tan	0.4		-				-			
Percent Chang	0.3						_			
9 8	0.2									
# 2	0.2									
ㅋь	0.1									
5 5						_	-	-		
s .e	0.0									
Absolute I Resistance	0.0	0	250	500	1K	2K	4K	6K	8K	10K
Ľ.		Test Duration in Hours								

PART NUMBERING

S0303AF 50R0 F H B

RESISTANCE VALUE

Three digits (>1% tolerance) or four digits (1% and lower) are used with all leading digits significant. The last digit specifies the number of zeros to add. The letter "R" is used to represent the decimal for fractional ohmic values. B: Solderable W: Wire Bondable K: SN 62 bump M:80/20 Au/Sn bump

TEMPERATURE COEFFICIENT

E: 25 ppm H: 50 ppm K: 100 ppm

TOLERANCES

B: 0.1% F: 1% G: 2% J: 5%

PRODUCT FEATURES

 Frequency Range to 20GHz with excellent VSWR characteristics

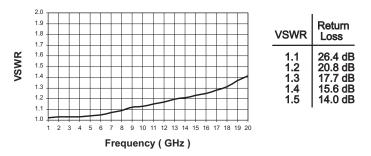
 Produced with the same stringent quality and reliability standards as our QPL S level Mil-PRF-55342 and space level products

- High stability thin film resistor element, 99.5% alumina substrate
- Tight tolerance and low TCR availability

FREQUENCY PERFORMANCE

State of the Art thin film high frequency chip resistors are produced with a tantalum-nitride based resistor element that is extremely stable with time, temperature, and frequency. The chips perform well over a wide frequency range, exhibiting low VSWR response from DC to 20 Ghz and higher. Solderable terminations allow the chips to be reflowed or hand soldered into microwave circuits easily while maintaining excellent return loss characteristics. Parasitic reactance is very low for these chips with capacitance being typically less than 0.1 pF.

The frequency response data plotted below shows an example of VSWR obtained for 50 ohm resistors tested (resistor element down) in pressure contact fixtures. Data for chips which are solder attached to matched circuit traces may exhibit even better performance.



Thin film 0303 high frequency chip resistors are also available in other terminations styles and material finishes for attachment to circuit boards by soldering, bonding, or epoxy mounting. High power chip designs on BeO can be provided for increased heat dissipation. Custom chip designs are available to provide optimum solutions for specific high frequency applications.

ADS and Characterization files are available upon request.

Consult our engineering department for specific performance needs.

PACKAGING

Packaging options available:

Waffle Pack - 400 per tray maximum

OPTIONS

- Optional high reliability screening or custom testing or other special requirements can also be furnished. Consult our factory with your special needs.
- · Also available on fused silica, product code: T